

ABSTRACT

5 A polishing apparatus capable of accurately determining a position of a
measurement point of a film thickness of a workpiece is disclosed. The polishing apparatus
includes: a polishing head configured to press a workpiece against a polishing pad on a
polishing table to polish the workpiece; a film-thickness sensor configured to measure a film
thickness at a measurement point on a surface of the workpiece; an infrared imaging device
10 configured to generate a first image and a second image of a feature region on the surface
of the workpiece at a predetermined time interval through a back surface of the workpiece;
and a processing controller configured to determine coordinates of the measurement point
on the surface of the workpiece based on the first image and the second image.

15 FIG. 2